X7S Dielectric



General Specifications



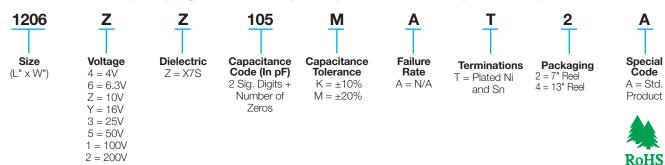
GENERAL DESCRIPTION

X7S formulations are called "temperature stable" ceramics and fall into EIA Class II materials. Its temperature variation of capacitance s within $\pm 22\%$ from -55°C to ± 125 °C. This capacitance change is non-linear.

Capacitance for X7S varies under the influence of electrical operating conditions such as voltage and frequency.

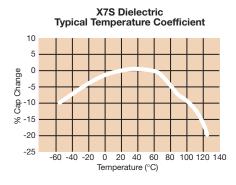
X7S dielectric chip usage covers the broad spectrum of industrial applications where known changes in capacitance due to applied voltages are acceptable.

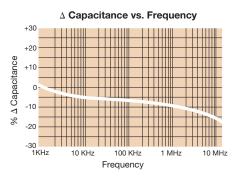
PART NUMBER (see page 2 for complete part number explanation)

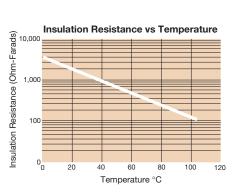


NOTE: Contact factory for availability of Tolerance Options for Specific Part Numbers.

TYPICAL ELECTRICAL CHARACTERISTICS

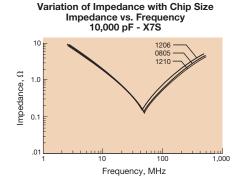


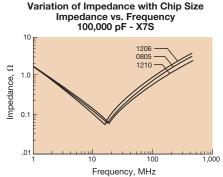




Impedance vs. Frequency 1,000 pF vs. 10,000 pF - X7S 0805 10.00 pF 1,000 pF 10,000 pF 10,000 pF 10,000 pF 1000 pF

Variation of Impedance with Cap Value





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Specifications and Test Methods

Parameter/Test		X7S Specification Limits	Measuring Conditions				
Operating Temperature Range		-55°C to +125°C	Temperature Cycle Chamber				
Capacitance Dissipation Factor		Within specified tolerance ≤ 5.0% for ≥ 100V DC rating ≤ 5.0% for ≥ 25V DC rating ≤ 10.0% for ≥ 10V DC rating ≤ 10.0% for ≤ 10V DC rating	Freq.: 1.0 kHz ± 10% Voltage: 1.0Vrms ± .2V For Cap > 10 µF, 0.5Vrms @ 120Hz				
Insulation Resistance		100,000MΩ or 1000MΩ - μ F, whichever is less	Charge device with 120 ± 5 secs @ ro	om temp/humidity			
Dielectric Strength		No breakdown or visual defects	Charge device with 300% of rated voltag 1-5 seconds, w/charge and discharge cu limited to 50 mA (max)				
Resistance to	Appearance	No defects	Deflection: 2mm				
	Capacitance Variation	≤ ±12%	Test Time: 30 seconds Tamm/sec				
Flexure Stresses	Dissipation Factor	Meets Initial Values (As Above)	V				
	Insulation Resistance	≥ Initial Value x 0.3	90 mm —				
Solder	rability	≥ 95% of each terminal should be covered with fresh solder	Dip device in eutectic solder at 230 \pm 5 for 5.0 \pm 0.5 seconds				
Resistance to Solder Heat	Appearance	No defects, <25% leaching of either end terminal					
	Capacitance Variation	≤ ±7.5%	Din davica in autactic	colder at 260°C for 60			
	Dissipation Factor	Meets Initial Values (As Above)	Dip device in eutectic solder at 260°C for 60 seconds. Store at room temperature for 24 ± 2 hours before measuring electrical properties.				
	Insulation Resistance	Meets Initial Values (As Above)					
	Dielectric Strength	Meets Initial Values (As Above)					
	Appearance	No visual defects	Step 1: -55°C ± 2°	30 ± 3 minutes			
	Capacitance Variation	≤ ±7.5%	Step 2: Room Temp	≤ 3 minutes			
Thermal Shock	Dissipation Factor	Meets Initial Values (As Above)	Step 3: +125°C ± 2°	30 ± 3 minutes			
SHOCK	Insulation Resistance	Meets Initial Values (As Above)	Step 4: Room Temp	≤ 3 minutes			
	Dielectric Strength	Meets Initial Values (As Above)	Repeat for 5 cycles ar 24 ± 2 hours at room				
	Appearance	No visual defects					
	Capacitance Variation	≤ ±12.5%	Charge device with 1.5 rated voltage (≤ 10V) in test chamber set at 125°C ± 2°C				
Load Life	Dissipation Factor	≤ Initial Value x 2.0 (See Above)	for 1000 hou	urs (+48, -0)			
	Insulation Resistance	≥ Initial Value x 0.3 (See Above)	Remove from test chamber and stabilize at room temperature for 24 ± 2 hours				
	Dielectric Strength	Meets Initial Values (As Above)	before measuring.				
Load Humidity	Appearance	No visual defects	Store in a test shamb	or eat at 85°C + 2°C/			
	Capacitance Variation	≤ ±12.5%	Store in a test chamber set at 85°C ± 2°C/ 85% ± 5% relative humidity for 1000 hours (+48, -0) with rated voltage applied.				
	Dissipation Factor	≤ Initial Value x 2.0 (See Above)					
	Insulation Resistance	≥ Initial Value x 0.3 (See Above)	room temperature	and humidity for			
	Dielectric Strength	Meets Initial Values (As Above)	- 24 ± 2 hours before measuring.				

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PREFERRED SIZES ARE SHADED

				E										
SIZE		0402		0603		0805	1206		1210					
Solderi	ing	Reflow/W	ave	Reflow/Wav	re Re	flow/Wave	Reflow/Wave Reflow Only		Reflow/W		Only			
Packag	ing	All Pape		All Paper		r/Embossed	Paper/Embossed				bossed			
(L) Length	mm (in.)	1.00 ± 0.1 (0.040 ± 0.0		1.60 ± 0.15 (0.063 ± 0.00		.01 ± 0.20 .079 ± 0.008)	3.20 ± 0.20 3.20 ± 0.20 (0.126 ± 0.008) (0.126 ± 0.008)							
(W) Width	mm (in.)	0.50 ± 0. (0.020 ± 0.0	10	0.81 ± 0.15 (0.032 ± 0.00	1	.25 ± 0.20 049 ± 0.008)	1.	.60 ± 0.20)	2.50 ± (0.098 ±	0.20			
(t) Terminal	mm (in.)	0.25 ± 0.15 (0.010 ± 0.006)		0.35 ± 0.15 (0.014 ± 0.006)		.50 ± 0.25 020 ± 0.010)	0.	50 ± 0.2	5	0.50 ± (0.020 ±	0.25			
	WVDC	6.3		6.3	-) (51.	4	10 50		100	6.3				
Cap	100							l l		i				
(pF)	150								_	× 111				
	220 330				_		Н.			\sim	>			
	470						~			,)) T			
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	1000							_						
	1500 2200								*t	7				
	3300						t							
	4700									I				
	6800													
Cap	0.010													
(μF	0.015 0.022													
	0.022	С			_									
	0.047	C												
	0.068	С												
	0.10 0.15	С												
	0.15													
	0.33			G										
	0.47			G										
	0.68			G G			_							
	1.0 1.5			G		N								
	2.2					N								
	3.3					N								
	4.7 10					N	Q		Q*					
	22				-		1			Z				
	47													
	100													
	WVDC	6.3 0402		6.3		4			50 100 6.3					
	SIZE			0603		0805		1206 1210		U				
Letter	А	С	Е	G	J	K	М		N	Р	Q	Х	Y	
Max.	0.33	0.56	0.71	0.90	0.94	1.02	1.27		40	1.52	1.90	2.29	2.54	
Thickness	(0.013)	(0.022)	(0.028)	(0.035)	(0.037)	(0.040)	(0.050)	(0.0	055)	(0.060)	(0.075)	(0.090)	(0.100)	
			PAPER	2						EMBC	SSED			

^{*}Contact Factory for Specifications

Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

AVX:

06036Z105KAT2A	04026Z104MAT2A	0603ZZ105KAT2A	0603ZZ105MAT2A	1206YZ105KAT2A	04026Z104KAT2A
04024Z105KAT2A	1206ZZ475KAT2A	1206ZZ475MAT2A	12106Z226KAT2A	12106Z226MAT2A	12061Z475MAT2A
12061Z475KAT2A	12065Z106KAT2A	12105Z106MAT2A			